



# 2 pF Off Capacitance, 1 pC Charge Injection, $\pm 15$ V/12 V 4:1 *i*CMOS™ Multiplexer

Preliminary Technical Data

ADG1204

## FEATURES

- 2 pF off capacitance
- 1 pC charge injection
- 33 V supply range
- 120  $\Omega$  on resistance
- Fully specified at +12 V,  $\pm 15$  V
- No  $V_L$  supply required
- 3 V logic-compatible inputs
- Rail-to-rail operation
- 14-lead TSSOP and 12-lead LFCSP
- Typical power consumption:  $<0.03 \mu\text{W}$

## APPLICATIONS

- Automatic test equipment
- Data acquisition systems
- Battery-powered systems
- Sample-and-hold systems
- Audio signal routing
- Communication systems

## GENERAL DESCRIPTION

The ADG1204 is a CMOS analog multiplexer, comprising four single channels designed on an *i*CMOS process. *i*CMOS (industrial-CMOS) is a modular manufacturing process that combines high voltage CMOS (complementary metal-oxide semiconductor) and bipolar technologies. It enables the development of a wide range of high performance analog ICs capable of 30-V operation in a footprint that no other generation of high voltage parts has been able to achieve. Unlike analog ICs using conventional CMOS processes, *i*CMOS components can tolerate high supply voltages, while providing increased performance, dramatically lower power consumption, and reduced package size.

The ultralow capacitance and charge injection of these switches make them ideal solutions for data acquisition and sample-and-hold applications, where low glitch and fast settling are required. Fast switching speed coupled with high signal bandwidth make the parts suitable for video signal switching. *i*CMOS construction ensures ultralow power dissipation, making the parts ideally suited for portable and battery powered instruments.

### Rev. PrD

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## FUNCTIONAL BLOCK DIAGRAM

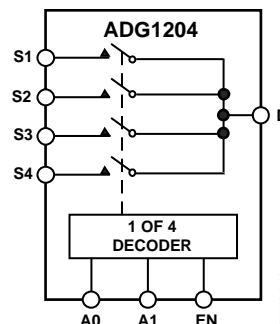


Figure 1.

The ADG1204 switches one of four inputs to a common output, D, as determined by the 3-bit binary address lines, A0, A1, and EN. Logic 0 on the EN pin disables the device. Each switch conducts equally well in both directions when on, and has an input signal range that extends to the supplies. In the off condition, signal levels up to the supplies are blocked. All switches exhibit break-before-make switching action. Inherent in the design is low charge injection for minimum transients when switching the digital inputs.

## PRODUCT HIGHLIGHTS

- 2 pF off capacitance ( $\pm 15$  V supply).
- 1 pC charge injection.
- 3 V logic-compatible digital inputs:  
 $V_{IH} = 2.0$  V,  $V_{IL} = 0.8$  V
- No  $V_L$  logic power supply required.
- Ultralow power dissipation:  $<0.03 \mu\text{W}$ .
- 14-lead TSSOP and 12-lead 3 mm  $\times$  3 mm LFCSP package.

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**REVISION HISTORY**

11/04—Revision PrD: Preliminary Version

# SPECIFICATIONS

## DUAL SUPPLY

$V_{DD} = 15\text{ V} \pm 10\%$ ,  $V_{SS} = -15\text{ V}$ ,  $GND = 0\text{ V}$ , unless otherwise noted.

Table 1.

Parameter	25°C	85°C	Y Version <sup>1</sup>	Unit	Test Conditions/Comments
<b>ANALOG SWITCH</b>					
Analog Signal Range			$V_{DD}$ to $V_{SS}$	V	
On Resistance ( $R_{ON}$ )	120	160	180	$\Omega$ typ $\Omega$ max	$V_S = \pm 10\text{ V}$ , $I_S = -10\text{ mA}$ ; Figure 21
On Resistance Match between Channels ( $\Delta R_{ON}$ )	5			$\Omega$ typ	$V_S = \pm 10\text{ V}$ , $I_S = -10\text{ mA}$
On Resistance Flatness ( $R_{FLAT(ON)}$ )	25		50	$\Omega$ max $\Omega$ typ $\Omega$ max	$V_S = -5\text{ V}, 0\text{ V}, +5\text{ V}$ ; $I_S = -10\text{ mA}$
<b>LEAKAGE CURRENTS</b>					
Source Off Leakage, $I_S$ (Off)	$\pm 0.01$ $\pm 0.5$	$\pm 1$	$\pm 5$	nA typ nA max	$V_{DD} = +10\text{ V}$ , $V_{SS} = -10\text{ V}$ $V_S = 0\text{ V}/10\text{ V}$ , $V_D = 10\text{ V}/0\text{ V}$ ; Figure 22
Drain Off Leakage, $I_D$ (Off)	$\pm 0.01$ $\pm 0.5$	$\pm 1$	$\pm 5$	nA typ nA max	$V_S = 0\text{ V}/10\text{ V}$ , $V_D = 10\text{ V}/0\text{ V}$ ; Figure 22
Channel On Leakage, $I_D$ , $I_S$ (On)	$\pm 0.04$ $\pm 1$	$\pm 2$	$\pm 5$	nA typ nA max	$V_S = V_D = 0\text{ V}$ or $10\text{ V}$ ; Figure 23
<b>DIGITAL INPUTS</b>					
Input High Voltage, $V_{INH}$			2.0	V min	
Input Low Voltage, $V_{INL}$			0.8	V max	
Input Current, $I_{INL}$ or $I_{INH}$	0.005		$\pm 0.5$	$\mu\text{A}$ typ $\mu\text{A}$ max	$V_{IN} = V_{INL}$ or $V_{INH}$
Digital Input Capacitance, $C_{IN}$	5			pF typ	
<b>DYNAMIC CHARACTERISTICS<sup>2</sup></b>					
Transition Time, $t_{TRANS}$	40			ns typ ns max	$R_L = 50\ \Omega$ , $C_L = 35\text{ pF}$ $V_S = \pm 10\text{ V}$ ; Figure 24
$t_{ON}$ (EN)	40		90	ns typ ns max	$R_L = 50\ \Omega$ , $C_L = 35\text{ pF}$ $V_S = \pm 10\text{ V}$ ; Figure 24
$t_{OFF}$ (EN)	20		40	ns typ ns max	$R_L = 50\ \Omega$ , $C_L = 35\text{ pF}$ $V_S = \pm 10\text{ V}$ ; Figure 24
Break-before-Make Time Delay, $t_D$	15		1	ns typ ns min	$R_L = 50\ \Omega$ , $C_L = 35\text{ pF}$ $V_{S1} = V_{S2} = 10\text{ V}$ ; Figure 25
Charge Injection	1			pC typ	$V_S = 0\text{ V}$ , $R_S = 0\ \Omega$ , $C_L = 1\text{ nF}$ ; Figure 26
Off Isolation	75			dB typ	$R_L = 50\ \Omega$ , $C_L = 5\text{ pF}$ , $f = 1\text{ MHz}$ ; Figure 27
Channel-to-Channel Crosstalk	85			dB typ	$R_L = 50\ \Omega$ , $C_L = 5\text{ pF}$ , $f = 1\text{ MHz}$ ; Figure 28
Total Harmonic Distortion + Noise	0.002			% typ	$R_L = 600\ \Omega$ , $5\text{ V rms}$ , $f = 20\text{ Hz}$ to $20\text{ kHz}$
-3 dB Bandwidth	700			MHz typ	$R_L = 50\ \Omega$ , $C_L = 5\text{ pF}$ ; Figure 29
$C_S$ (Off)	2			pF typ	
$C_D$ (Off)	7			pF typ	
$C_D$ , $C_S$ (On)	4			pF typ	
<b>POWER REQUIREMENTS</b>					
$I_{DD}$	0.001		5.0	$\mu\text{A}$ typ $\mu\text{A}$ max	$V_{DD} = +16.5\text{ V}$ , $V_{SS} = -16.5\text{ V}$ Digital Inputs = $0\text{ V}$ or $V_{DD}$
$I_{DD}$	150		300	$\mu\text{A}$ typ $\mu\text{A}$ max	Digital Inputs = $5\text{ V}$
$I_{SS}$	0.001		5.0	$\mu\text{A}$ typ $\mu\text{A}$ max	Digital Inputs = $0\text{ V}$ or $V_{DD}$

Parameter	25°C	85°C	Y Version <sup>1</sup>	Unit	Test Conditions/Comments
I <sub>GND</sub>	0.001			μA typ	Digital Inputs = 0 V or V <sub>DD</sub>
I <sub>GND</sub>	150		5.0	μA max	Digital Inputs = 5 V
			300	μA typ	
				μA max	

<sup>1</sup> Y Version temperature range is -40°C to +125°C.

<sup>2</sup> Guaranteed by design, not subject to production test.

V<sub>DD</sub> = +5 V ± 10%, V<sub>SS</sub> = -5 V ± 10%, GND = 0 V, unless otherwise noted.

**Table 2.**

Parameter	25°C	85°C	Y Version <sup>1</sup>	Unit	Test Conditions/Comments
<b>ANALOG SWITCH</b>					
Analog Signal Range			V <sub>SS</sub> to V <sub>DD</sub>	V	
On Resistance (R <sub>ON</sub> )	220			Ω typ	V <sub>S</sub> = ±3.3 V, I <sub>S</sub> = -10 mA; Figure 21
				Ω max	
On Resistance Match between Channels (ΔR <sub>ON</sub> )	10			Ω typ	
				Ω max	V <sub>S</sub> = ±3.3 V, I <sub>S</sub> = -10 mA
On Resistance Flatness (R <sub>FLAT(ON)</sub> )	30			Ω typ	V <sub>S</sub> = ±3.3 V, I <sub>S</sub> = -10 mA
				Ω max	
<b>LEAKAGE CURRENTS</b>					
Source Off Leakage, I <sub>S</sub> (Off)	±0.01			nA typ	V <sub>DD</sub> = 5.5 V, V <sub>SS</sub> = -5.5 V
	±0.5	±1	±5	nA max	V <sub>D</sub> = ±4.5 V, V <sub>S</sub> = ±4.5 V; Figure 22
Drain Off Leakage, I <sub>D</sub> (Off)	±0.01			nA typ	V <sub>D</sub> = ±4.5 V, V <sub>S</sub> = ±4.5 V; Figure 22
	±0.5	±1	±5	nA max	
Channel On Leakage, I <sub>D</sub> , I <sub>S</sub> (On)	±0.04			nA typ	V <sub>D</sub> = V <sub>S</sub> = ±4.5 V; Figure 23
	±1	±2	±5	nA max	
<b>DIGITAL INPUTS</b>					
Input High Voltage, V <sub>INH</sub>		2.0		V min	
Input Low Voltage, V <sub>INL</sub>		0.8		V max	
Input Current, I <sub>INL</sub> or I <sub>INH</sub>	0.005		±0.5	μA typ	V <sub>IN</sub> = V <sub>INL</sub> or V <sub>INH</sub>
				μA max	
Digital Input Capacitance, C <sub>IN</sub>	5			pF typ	
<b>DYNAMIC CHARACTERISTICS<sup>2</sup></b>					
t <sub>ON</sub>	160			ns typ	R <sub>L</sub> = 300 Ω, C <sub>L</sub> = 35 pF
				ns max	V <sub>S</sub> = 3 V; Figure 24
t <sub>OFF</sub>	60			ns typ	R <sub>L</sub> = 300 Ω, C <sub>L</sub> = 35 pF
				ns max	V <sub>S</sub> = 3 V; Figure 24
Break-before-Make Time Delay, t <sub>D</sub>	50			ns typ	R <sub>L</sub> = 300 Ω, C <sub>L</sub> = 35 pF
				ns min	V <sub>S1</sub> = V <sub>S2</sub> = 3 V; Figure 25
Charge Injection	20			pC typ	V <sub>S</sub> = 0 V, R <sub>S</sub> = 0 Ω, C <sub>L</sub> = 1 nF; Figure 26
				pC max	
Off Isolation	56			dB typ	R <sub>L</sub> = 50 Ω, C <sub>L</sub> = 5 pF, f = 1 MHz; Figure 27
Channel-to-Channel Crosstalk	60			dB typ	R <sub>L</sub> = 50 Ω, C <sub>L</sub> = 5 pF, f = 1 MHz; Figure 28
-3 dB Bandwidth	20			MHz typ	R <sub>L</sub> = 50 Ω, C <sub>L</sub> = 5 pF; Figure 29
C <sub>S</sub> (Off)	15			pF typ	f = 1 MHz
C <sub>D</sub> (Off)				pF typ	f = 1 MHz
C <sub>D</sub> , C <sub>S</sub> (On)	100			pF typ	f = 1 MHz

Parameter	25°C	85°C	Y Version <sup>1</sup>	Unit	Test Conditions/Comments
<b>POWER REQUIREMENTS</b>					
I <sub>DD</sub>	0.001			μA typ	V <sub>DD</sub> = +5.5 V, V <sub>SS</sub> = -5.5 V Digital Inputs = 0 V or 5.5 V
I <sub>SS</sub>	0.001		5.0	μA max	
			5.0	μA typ	Digital Inputs = 0 V or 5.5 V
				μA max	

<sup>1</sup> Y Version temperature range is -40°C to +125°C.

<sup>2</sup> Guaranteed by design, not subject to production test.

### SINGLE SUPPLY

V<sub>DD</sub> = 12 V ± 10%, V<sub>SS</sub> = 0 V, GND = 0 V, unless otherwise noted.

Table 3.

Parameter	25°C	85°C	Y Version <sup>1</sup>	Unit	Test Conditions/Comments
<b>ANALOG SWITCH</b>					
Analog Signal Range			0 V to V <sub>DD</sub>	V	
On Resistance (R <sub>ON</sub> )	220			Ω typ	V <sub>S</sub> = 10 V, I <sub>S</sub> = -10 mA; Figure 21
				Ω max	
On Resistance Match between Channels (ΔR <sub>ON</sub> )	1			Ω typ	V <sub>S</sub> = 10 V, I <sub>S</sub> = -10 mA
				Ω max	
On Resistance Flatness (R <sub>FLAT(ON)</sub> )	12			Ω typ	V <sub>S</sub> = 3 V, 6 V, 9 V; I <sub>S</sub> = -10 mA
<b>LEAKAGE CURRENTS</b>					
Source Off Leakage, I <sub>S</sub> (Off)	±0.01			nA typ	V <sub>DD</sub> = 12 V V <sub>S</sub> = 1 V/10 V, V <sub>D</sub> = 10 V/1 V; Figure 22
	±0.5	±1	±5	nA max	
Drain Off Leakage, I <sub>D</sub> (Off)	±0.01			nA typ	V <sub>S</sub> = 1 V/10 V, V <sub>D</sub> = 10 V/1 V; Figure 22
	±0.5	±1	±5	nA max	
Channel On Leakage, I <sub>D</sub> , I <sub>S</sub> (On)	±0.04			nA typ	V <sub>S</sub> = V <sub>D</sub> = 1 V or 10 V; Figure 23
	±1	±2	±5	nA max	
<b>DIGITAL INPUTS</b>					
Input High Voltage, V <sub>INH</sub>			2.0	V min	
Input Low Voltage, V <sub>INL</sub>			0.8	V max	
Input Current, I <sub>INL</sub> or I <sub>INH</sub>	0.001			μA typ	V <sub>IN</sub> = V <sub>INL</sub> or V <sub>INH</sub>
				μA max	
Digital Input Capacitance, C <sub>IN</sub>	5			pF typ	
<b>DYNAMIC CHARACTERISTICS<sup>2</sup></b>					
Transition Time, t <sub>TRANS</sub>	40			ns typ	R <sub>L</sub> = 50 Ω, C <sub>L</sub> = 35 pF
				ns max	V <sub>S</sub> = ±10 V; Figure 24
t <sub>ON</sub> (EN)	50			ns typ	R <sub>L</sub> = 50 Ω, C <sub>L</sub> = 35 pF
				ns max	V <sub>S</sub> = 8 V; Figure 24
t <sub>OFF</sub> (EN)	15			ns typ	R <sub>L</sub> = 50 Ω, C <sub>L</sub> = 35 pF
				ns max	V <sub>S</sub> = 8 V; Figure 24
Break-before-Make Time Delay, t <sub>D</sub>	15			ns typ	R <sub>L</sub> = 50 Ω, C <sub>L</sub> = 35 pF
				ns min	V <sub>S1</sub> = V <sub>S2</sub> = 8 V; Figure 25
Charge Injection	5			pC typ	V <sub>S</sub> = 0 V, R <sub>S</sub> = 0 Ω, C <sub>L</sub> = 1 nF; Figure 26
Off Isolation	75			dB typ	R <sub>L</sub> = 50 Ω, C <sub>L</sub> = 5 pF, f = 1 MHz; Figure 27
Channel-to-Channel Crosstalk	85			dB typ	R <sub>L</sub> = 50 Ω, C <sub>L</sub> = 5 pF, f = 1 MHz; Figure 28
-3 dB Bandwidth	700			MHz typ	R <sub>L</sub> = 50 Ω, C <sub>L</sub> = 5 pF; Figure 29
C <sub>S</sub> (Off)	2			pF typ	
C <sub>D</sub> (Off)	2			pF typ	
C <sub>D</sub> , C <sub>S</sub> (On)	4			pF typ	

Parameter	25°C	85°C	Y Version <sup>1</sup>	Unit	Test Conditions/Comments
POWER REQUIREMENTS					$V_{DD} = 13.2\text{ V}$
$I_{DD}$	0.001		5.0	$\mu\text{A typ}$	Digital inputs = 0 V or $V_{DD}$
$I_{DD}$	150		300	$\mu\text{A max}$	Digital inputs = 5 V
				$\mu\text{A typ}$	
				$\mu\text{A max}$	

<sup>1</sup> Y Version temperature range is  $-40^{\circ}\text{C}$  to  $+125^{\circ}\text{C}$ .

<sup>2</sup> Guaranteed by design, not subject to production test.

## ABSOLUTE MAXIMUM RATINGS

T<sub>A</sub> = 25°C, unless otherwise noted.

Table 4.

Parameter	Rating
V <sub>DD</sub> to V <sub>SS</sub>	38 V
V <sub>DD</sub> to GND	-0.3 V to +25 V
V <sub>SS</sub> to GND	+0.3 V to -25 V
Analog Inputs <sup>1</sup>	V <sub>SS</sub> - 0.3 V to V <sub>DD</sub> + 0.3 V
Digital Inputs	GND - 0.3 V to V <sub>DD</sub> + 0.3 V or 30 mA, whichever occurs first
Peak Current, S or D	100 mA (pulsed at 1 ms, 10% duty cycle max)
Continuous Current, S or D	30 mA
Operating Temperature Range	
Industrial (B Version)	-40°C to +85°C
Automotive (Y Version)	-40°C to +125°C
Storage Temperature Range	-65°C to +150°C
Junction Temperature	150°C
14-Lead TSSOP, θ <sub>JA</sub> Thermal Impedance	150.4°C/W
12-Lead LFCSP, θ <sub>JA</sub> Thermal Impedance	30.4°C/W
Lead Temperature, Soldering	
Vapor Phase (60 s)	215°C
Infrared (15 s)	220°C

<sup>1</sup> Overvoltages at IN, S, or D are clamped by internal diodes. Current should be limited to the maximum ratings given.

### ESD CAUTION

ESD (electrostatic discharge) sensitive device. Electrostatic charges as high as 4000 V readily accumulate on the human body and test equipment and can discharge without detection. Although this product features proprietary ESD protection circuitry, permanent damage may occur on devices subjected to high energy electrostatic discharges. Therefore, proper ESD precautions are recommended to avoid performance degradation or loss of functionality.

Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only; functional operation of the device at these or any other conditions above those listed in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability. Only one absolute maximum rating may be applied at any one time.

### TRUTH TABLE

Table 5.

EN	A1	A0	S1	S2	S3	S4
0	X	X	Off	Off	Off	Off
1	0	0	On	Off	Off	Off
1	0	1	Off	On	Off	Off
1	1	0	Off	Off	On	Off
1	1	1	Off	Off	Off	On



PIN CONFIGURATIONS AND FUNCTION DESCRIPTIONS

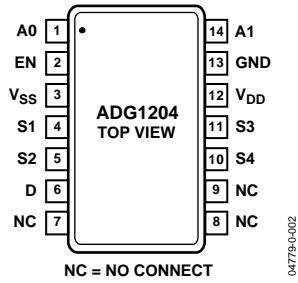


Figure 2. TSSOP Pin Configuration

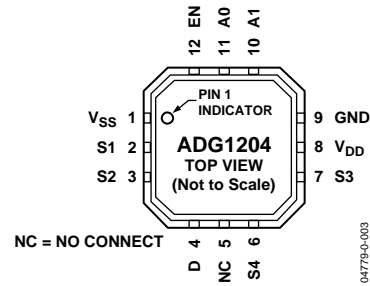


Figure 3. LFCSP Pin Configuration

Table 6. Pin Function Descriptions

Pin No.		Mnemonic	Function
TSSOP	LFCSP		
1	11	A0	Logic Control Input.
2	12	EN	Active High Digital Input. When low, the device is disabled and all switches are off. When high, Ax logic inputs determine on switches.
3	1	V <sub>SS</sub>	Most Negative Power Supply Potential.
4	2	S1	Source Terminal. Can be an input or an output.
5	3	S2	Source Terminal. Can be an input or an output.
6	4	D	Drain Terminal. Can be an input or an output.
7-9	5	NC	No Connection.
10	6	S4	Source Terminal. Can be an input or an output.
11	7	S3	Source Terminal. Can be an input or an output.
12	8	V <sub>DD</sub>	Most Positive Power Supply Potential.
13	9	GND	Ground (0 V) Reference.
14	10	A1	Logic Control Input.



## TERMINOLOGY

**I<sub>DD</sub>**

The positive supply current.

**I<sub>SS</sub>**

The negative supply current.

**V<sub>D</sub> (V<sub>S</sub>)**

The analog voltage on Terminals D and S.

**R<sub>ON</sub>**

The ohmic resistance between D and S.

**R<sub>FLAT(ON)</sub>**

Flatness is defined as the difference between the maximum and minimum value of on resistance, as measured over the specified analog signal range.

**I<sub>S</sub> (Off)**

The source leakage current with the switch off.

**I<sub>D</sub> (Off)**

The drain leakage current with the switch off.

**I<sub>D</sub>, I<sub>S</sub> (On)**

The channel leakage current with the switch on.

**V<sub>INL</sub>**

The maximum input voltage for Logic 0.

**V<sub>INH</sub>**

The minimum input voltage for Logic 1.

**I<sub>INL</sub> (I<sub>INH</sub>)**

The input current of the digital input.

**C<sub>S</sub> (Off)**

The off switch source capacitance, which is measured with reference to ground.

**C<sub>D</sub> (Off)**

The off switch drain capacitance, which is measured with reference to ground.

**C<sub>D</sub>, C<sub>S</sub> (On)**

The on switch capacitance, which is measured with reference to ground.

**C<sub>IN</sub>**

The digital input capacitance.

**t<sub>ON</sub> (EN)**

The delay between applying the digital control input and the output switching on. See Figure 24, Test Circuit 4.

**t<sub>OFF</sub> (EN)**

The delay between applying the digital control input and the output switching off.

**Charge Injection**

A measure of the glitch impulse transferred from the digital input to the analog output during switching.

**Off Isolation**

A measure of unwanted signal coupling through an off switch.

**Crosstalk**

A measure of unwanted signal that is coupled through from one channel to another as a result of parasitic capacitance.

**Bandwidth**

The frequency at which the output is attenuated by 3 dB.

**On Response**

The frequency response of the on switch.

**Insertion Loss**

The loss due to the on resistance of the switch.

**THD + N**

The ratio of the harmonic amplitude plus noise of the signal to the fundamental.

**t<sub>TRANS</sub>**

The delay time between the 50% and 90% points of the digital input and switch on condition when switching from one address state to another.

### TYPICAL PERFORMANCE CHARACTERISTICS



Figure 4. On Resistance as a Function of  $V_D$  ( $V_S$ ) for Single Supply



Figure 7. On Resistance as a Function of  $V_D$  ( $V_S$ ) for Different Temperatures, Single Supply



Figure 5. On Resistance as a Function of  $V_D$  ( $V_S$ ) for Dual Supply



Figure 8. On Resistance as a Function of  $V_D$  ( $V_S$ ) for Different Temperatures, Dual Supply



Figure 6. On Resistance as a Function of  $V_D$  ( $V_S$ ) for Different Temperatures, Single Supply



Figure 9. Leakage Currents as a Function of  $V_D$  ( $V_S$ )



Figure 10. Leakage Currents as a Function of  $V_D$  ( $V_S$ )



Figure 13. Leakage Currents as a Function of Temperature



Figure 11. Leakage Currents as a Function of  $V_D$  ( $V_S$ )



Figure 14. Supply Currents vs. Input Switching Frequency



Figure 12. Leakage Currents as a Function of Temperature



Figure 15. Charge Injection vs. Source Voltage



Figure 16.  $t_{on}/t_{off}$  Times vs. Temperature



Figure 19. On Response vs. Frequency



Figure 17. Off Isolation vs. Frequency



Figure 20. THD + N vs. Frequency



Figure 18. Crosstalk vs. Frequency

TEST CIRCUITS

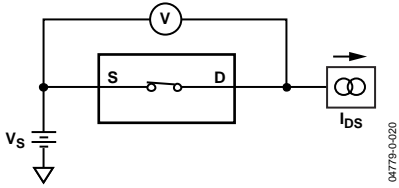


Figure 21. Test Circuit 1—On Resistance

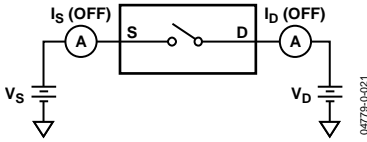


Figure 22. Test Circuit 2—Off Leakage

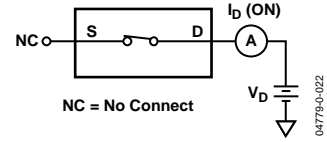


Figure 23. Test Circuit 3—On Leakage

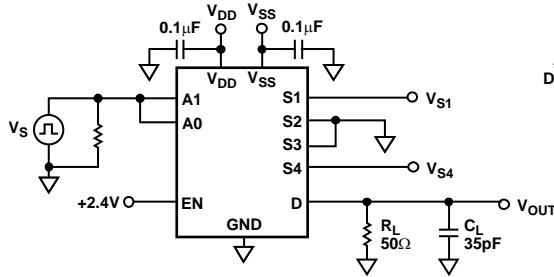


Figure 24. Test Circuit 4—Address to Output Switching Times

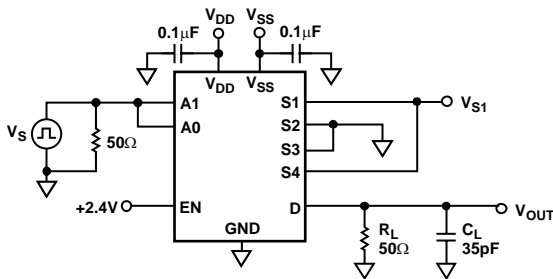
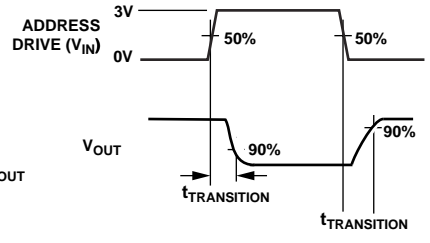


Figure 25. Test Circuit 5—Break-before-Make Time

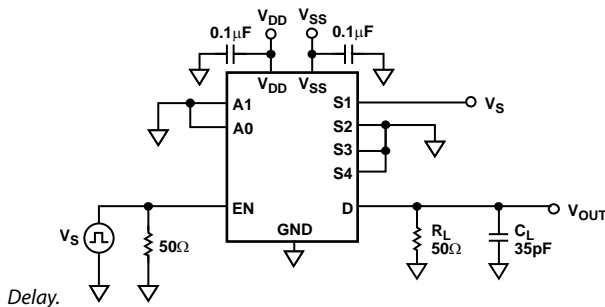
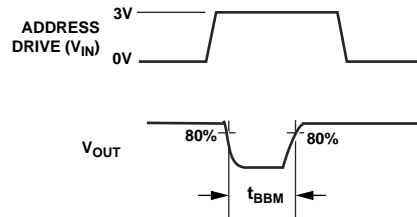
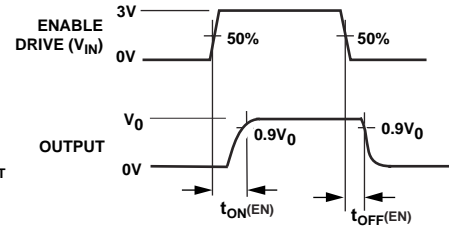


Figure 26. Test Circuit 6—Enable to Output Switching Delay



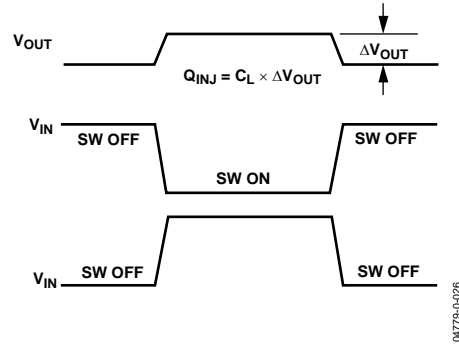
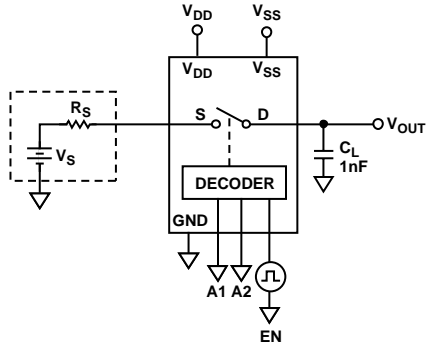
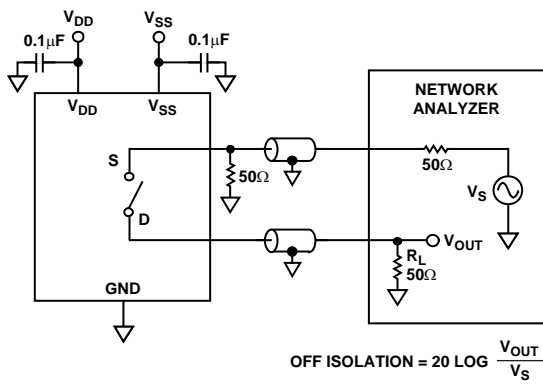


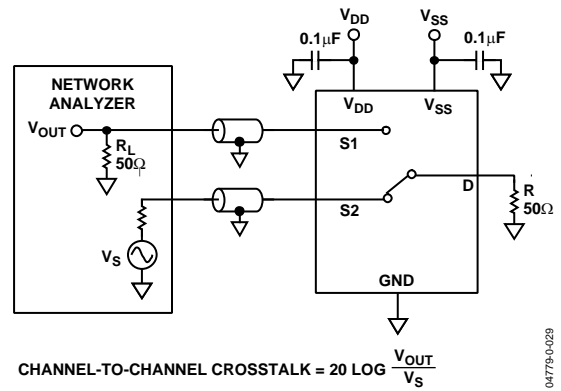
Figure 27. Test Circuit 7—Charge Injection



OFF ISOLATION =  $20 \text{ LOG } \frac{V_{OUT}}{V_S}$

04779-0-027

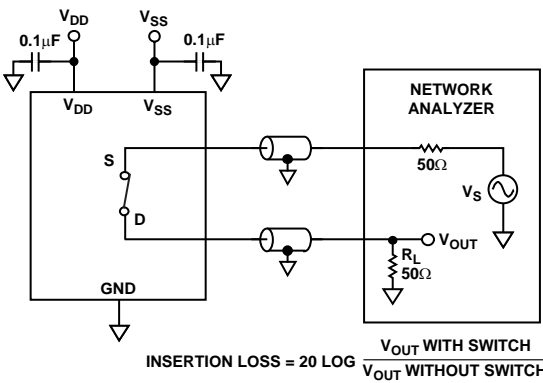
Figure 28. Test Circuit 8—Off Isolation



CHANNEL-TO-CHANNEL CROSSTALK =  $20 \text{ LOG } \frac{V_{OUT}}{V_S}$

04779-0-029

Figure 30. Test Circuit 10—Channel-to-Channel Crosstalk



INSERTION LOSS =  $20 \text{ LOG } \frac{V_{OUT \text{ WITH SWITCH}}}{V_{OUT \text{ WITHOUT SWITCH}}}$

04779-0-028

Figure 29. Test Circuit 9—Bandwidth

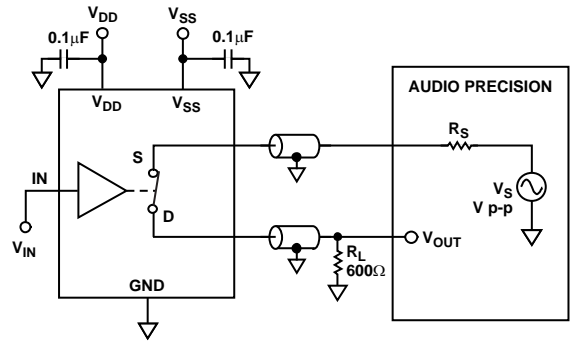


Figure 31. Test Circuit 11—THD + Noise

04779-0-030

### OUTLINE DIMENSIONS

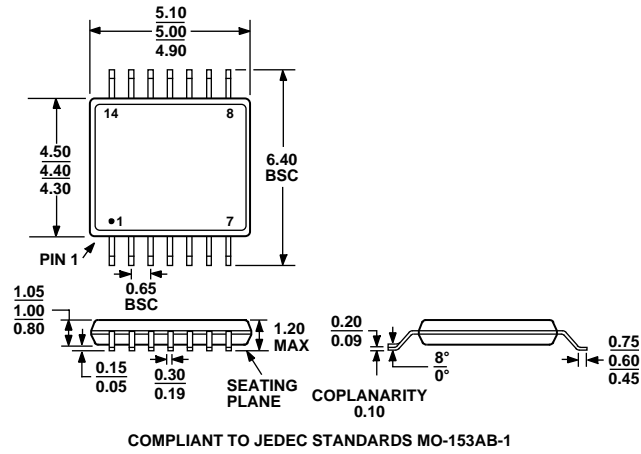


Figure 32. 14-Lead Thin Shrink Small Outline Package [TSSOP] (RU-14)  
Dimension shown in millimeters

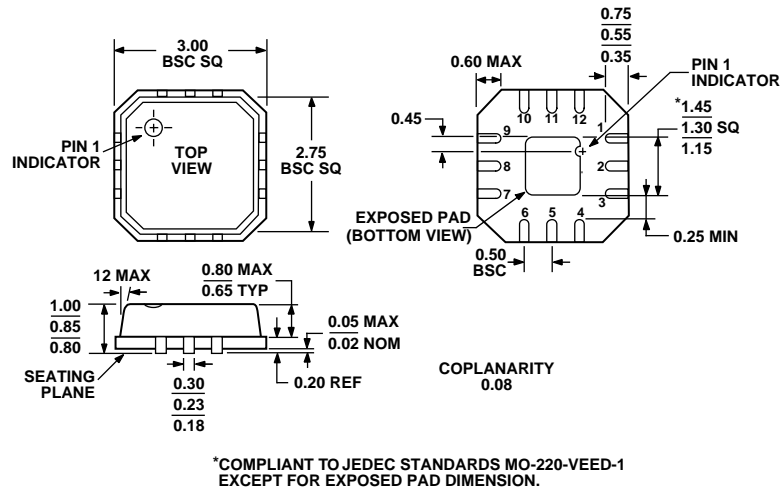


Figure 33. 12-Lead Lead Frame Chip Scale Package [VQ\_LFCSP] 3 mm x 3 mm Body, Very Thin Quad (CP-12-1)  
Dimensions shown in inches and (millimeters)

### ORDERING GUIDE

Model	Temperature Range	Package Description	Package Option
ADG1204YRU	-40°C to +125°C	Thin Shrink Small Outline Package (TSSOP)	RU-14
ADG1204YCP	-40°C to +125°C	Lead Frame Chip Scale Package (LFCSP)	CP-12-1

**NOTES**